

TR7007 SII Plus SERIES



3D SOLDER
PASTE INSPECTION

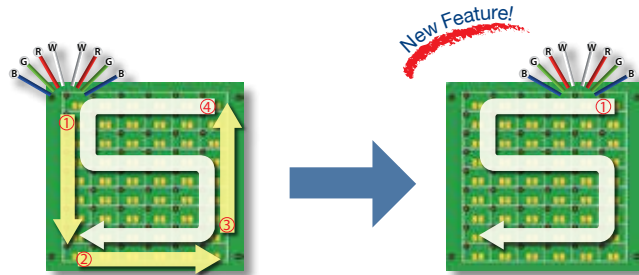
TR7007 SII Plus FEATURES

TR7007 SII Plus

Highly Accurate shadow-free SPI solution with class-leading inspection performance and easy programming brings maximum value to your production line.

Unmatched Speed & Throughput

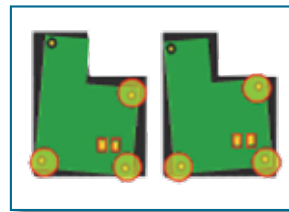
Industry-leading inspection speed using TRI's Dynamic Imaging technology keeps up with the production line beat without slowing down for even the most complex boards with multiple local fiducial marks. TRI's unique solution guarantees perfect results while reducing expensive cycle time.



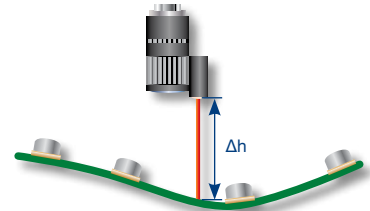
TRI's Color Imaging needs to scan only one Fiducial Mark on every board, saving cycle time.

Stable and Reliable Performance

Fully optimized for maximum stability, the TR7007 SII Plus delivers reliable inspection results 24 hours a day, and automatically compensates for manufacturing tolerances and board warp.

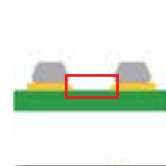


Reliable warp compensation and local fiducial marks guarantee stable results under any conditions.

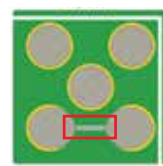


Unique Low Bridge Inspection

World's first inspection of low solder paste bridges under 30 μm ensures no printing defects are missed, and guarantees accurate results under any conditions.



3D Height Profile cannot reveal low bridges

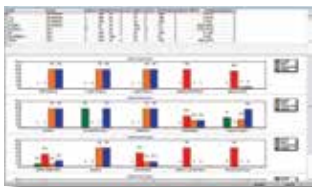


Top Color View

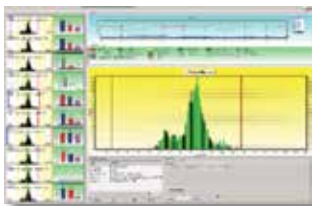


2D+3D Image with clear low bridge defect

SPC



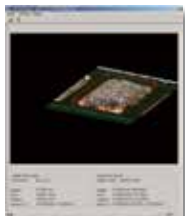
Statistical Report



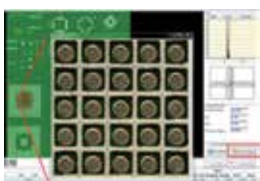
Multi-panel Histogram



Solder Height Distribution



3D Color Image



SPC 2D Real Image Query

Intuitive SPC Display

Full panel maps and real color images allow engineers to quickly monitor and diagnose problematic areas on the stencil, saving management time and reducing rework costs.

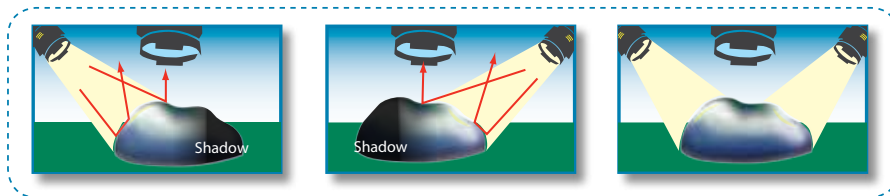
Intelligent Easy Programming Interface

Rapid intelligent 5-step programming interface ensures fast changeovers, minimal idle time and helps reduce operator work load.



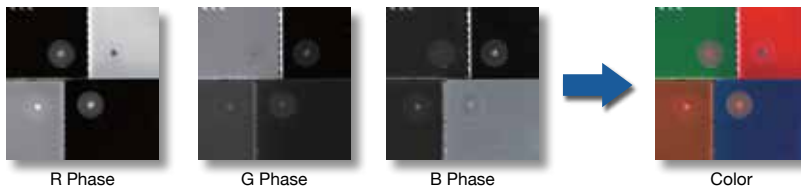
Shadow Free Inspection Technology

Dual projection design and intelligent software ensure the TR7007 SII Plus delivers completely shadow-free inspection results and eliminates problems with specular reflections.



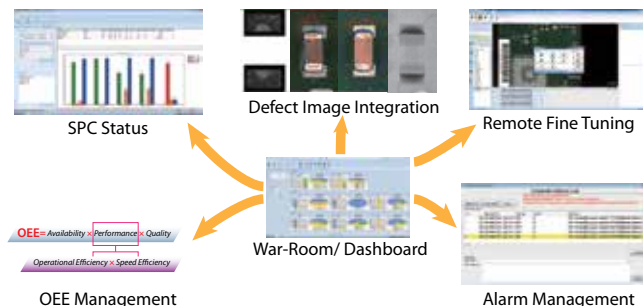
Multi-Color Vision for any PCB

Multi-phase color lighting guarantees accurate inspection results on any PCB color and finish combination, without sacrificing inspection speed.



Yield Management System 4.0

YMS 4.0 provides real-time inspection status across SPI, AOI and AXI systems and monitors SPC and Alarm status, and supports remote fine-tune throughout the SMT line. The centralized inspection management provides top 5 to 10 defects and defective images, OEE review and management, issue and root cause drill down line by line, by station and by process, which improves quality and productivity analysis. YMS 4.0 supports Industry 4.0 initiative.



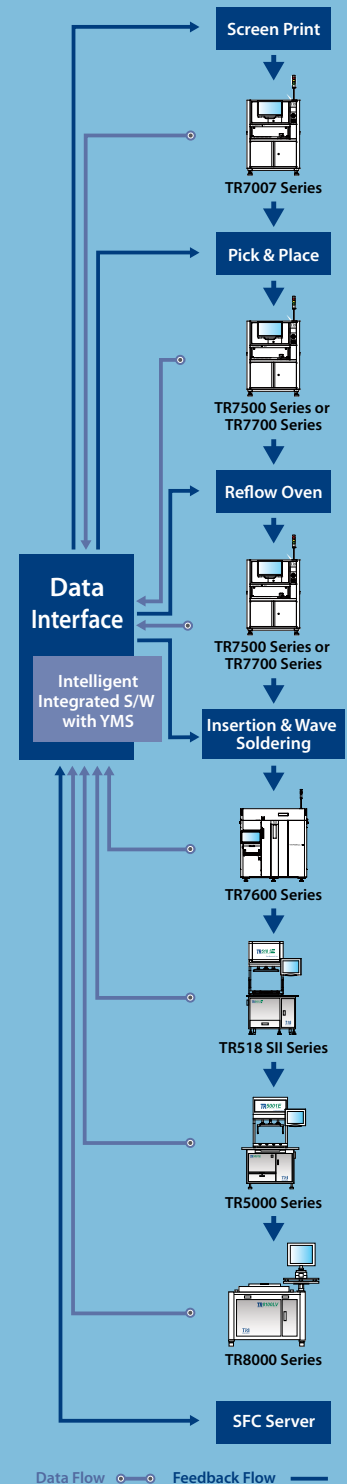
Closed Loop Function

TRI SPI systems share inspection results with connected SMT line equipment to help improve production yields and stabilize production quality while minimizing line stops and reducing production costs.

High Production Value = Maximum Cost Savings

- Industry Leading Inspection Speed
- Stable and Reliable Results
- Early Defect Detection
- Enhanced 100% Defect Coverage
- 98% Rework Cost Reduction

Yield Management System*



- Inspection results and data integration
 - Real time SPC and production yield management
 - Quality reports and closed loop tracking
 - Support defect component analysis and improvements
 - Knowledge Management (KM)
 - Productivity and Quality Management
- * Optional

Optical & Imaging System

Camera Type	4 Mpx camera	
Optical Resolution	10 μ m or 15 μ m (factory setting)	
Field of View	10 μ m	20.0 x 20.0 mm (0.79 x 0.79 in)
	15 μ m	30.0 x 30.0 mm (1.18 x 1.18 in)

Inspection Functions

Defects Detected	Insufficient Paste, Excessive Paste, Shape Deformity, Missing Paste & Bridging
Measurement	Height, area, volume and offset

Mechanical Stage

X-axis linear motor and linear scale with DSP-based motion controller

XY Resolution	0.5 μ m
Z Resolution	1 μ m

Inspection Speed

10 μ m	Up to 90 cm ² /sec
15 μ m	Up to 200 cm ² /sec

Inspection Performance

Volume Repeatability	Calibration Target (at 3 σ)	<1% on TRI calibration target
Height Repeatability	Calibration Target (at 3 σ)	<1% on TRI calibration target
	Solder GR&R ($\pm$ 50% Tolerance)	<<10% at 6 σ
Height Resolution	0.4 μ m	
Height Accuracy	1.5 μ m on calibration target	
Max. Solder Paste Size	12800 x 10240 μ m at 10 μ m	
Min. Solder Paste Size	100 x 100 μ m at 10 μ m	
Min. Solder Paste Pitch	100 μ m	
Max. Height Range	10 μ m	600 μ m
	15 μ m	550 μ m



PCB and Conveyor System

Min. PCB Size	50 x 50 mm (1.97 x 1.97 in.)		
Max. PCB Size	TR7007M SII Plus	TR7007 SII Plus	TR7007L SII Plus
	350 x 350 mm (13.8 x 13.8 in.)	510 x 460 mm (20.1 x 18.1 in.)	660 x 610 mm (26.0 x 24.0 in.)
	TR7007 SII Plus DL		
	510 x 310 mm x 2 lanes (20.1 x 12.2 in. x 2 lanes) 510 x 590 mm x 1 lane (20.1 x 23.2 in. x 1 lane)		
PCB Thickness	0.6 - 5 mm		
PCB Transport Height	880 - 920 mm (34.6 - 36.2 in.)		
Max. PCB Weight	3 kg (6.61 lbs)		
PCB Carrier/Fixing	Belt/Pneumatic		
Clearance			
Top	25 mm (0.98 in.)		
Bottom	40 mm (1.58 in.)		
Edge	3 mm (0.12 in.)		

Dimensions

Dimensions (W x D x H) /Weight	TR7007M SII Plus	TR7007 SII Plus	TR7007L SII Plus
	1000 x 1555 x 1500 mm (39.4 x 61.2 x 59.1 in.) (not including signal tower, height: 520 mm)	1100 x 1570 x 1550 mm (43.3 x 61.8 x 61.0 in.) (not including signal tower, height: 520 mm)	1300 x 1610 x 1560 mm (51.2 x 63.4 x 61.4 in.) (not including signal tower, height: 520 mm)
	870 kg (1918 lbs)	950 kg (2094 lbs)	1250 kg (2756 lbs)
	TR7007 SII Plus DL		
	1100 x 1770 x 1560 mm (43.3 x 65.7 x 61.0 in.) (not including signal tower, height: 520 mm)		
	1100 kg (2425 lbs)		
Power Requirement	200 - 240 V, single phase, 50/60 Hz 3 kVA		
Air Requirement	72 psi - 87 psi (5 - 6 Bar)		

Optional

SPC, Offline Editor, Gerber Tool, Barcode Scanner (linear & 2D) and Support Pins, Closed Loop Function, Dual Lane, Y-Axis Linear Motor, TRI's Yield Management System (YMS 4.0), YMS Lite

Headquarters

7F., No.45, Dexing West Rd.,
Shilin Dist., Taipei City
11158, Taiwan
TEL: +886-2-2832-8918
FAX: +886-2-2831-0567
E-Mail: sales@tri.com.tw
http://www.tri.com.tw

Linkou, Taiwan

No.256, Huaya 2nd Rd.,
Guishan Dist., Taoyuan
City 33383, Taiwan
TEL: +886-2-2832-8918
FAX: +886-3-328-6579

Hsinchu, Taiwan

7F., No.47, Guangming 6th
Rd., Zhubei City, Hsinchu
County 30268, Taiwan
TEL: +886-2-2832-8918
FAX: +886-3-553-9786

Shenzhen, China

5F3, Guangxia Rd., Shang-mei-lin
Area, Fu-Tian District, Shenzhen,
Guangdong, 518049, China
TEL: +86-755-83112668
FAX: +86-755-83108177
E-mail: shenzhen@cn.tri.com.tw

Suzhou, China

B Unit, Building 4, 78 Xinglin
St., Suzhou Industrial Park,
215123, China
TEL: +86-512-68250001
FAX: +86-512-68096639
E-mail: suzhou@cn.tri.com.tw

Shanghai, China

Room 6C, Building 14, Aly. 470,
Guiping Rd., Xuhui Dist.,
Shanghai, 200233, China
TEL: +86-21-54270101
FAX: +86-21-64957923
E-mail: shanghai@cn.tri.com.tw

USA

1923 Hartog Drive
San Jose, CA 95131 U.S.A
TEL: +1-408-567-9898
FAX: +1-408-567-9288
E-mail: triusa@tri.com.tw

Europe

O'Brien Strasse 14
91126 Schwabach
Germany
TEL: +49-9122-631-2127
FAX: +49-9122-631-2147
E-mail: trieurope@tri.com.tw

Japan

2-9-9 Midori, Sumida-ku,
Tokyo, 130-0021 Japan
TEL: +81-3-6273-0518
FAX: +81-3-6273-0519
E-mail: trijp@tri.com.tw

Korea

No.207 Daewoo-Technopia,
768-1 Wonsi-Dong, Danwon-Gu,
Ansan City, Gyeonggi-Do, Korea
TEL: +82-31-470-8858
FAX: +82-31-470-8859
E-mail: trikr@tri.com.tw

Malaysia

C11-1, Ground Floor, Lorong
Bayan Indah 3 Bay Avenue,
11900 Bayan Lepas Penang,
Malaysia
TEL: +604-6461171
E-mail: trimy@tri.com.tw

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